ABSTRACT OF THE DISCLOSURE

HEAT SINK FOR BALL GRID ARRAY PACKAGES

A molded circuit package and method of forming a molded circuit package which includes a heat sink, located directly over the circuit die, to spread the heat energy generated by the circuit die. The heat sink can have standoff members or can be a simple heat sink without standoff members. The circuit package in encapsulated using a molded encapsulant. The heat sink can be completely encapsulated by the encapsulation material or can have one surface exposed to the environment. The circuit die is attached to a carrier board. Since the carrier board does not need to act as a heat spreader, a very simple carrier board can be used.

(FIGURE 2 IS SUGGESTED FOR PUBLICATION)